

FIG. 1

FIG. 2A

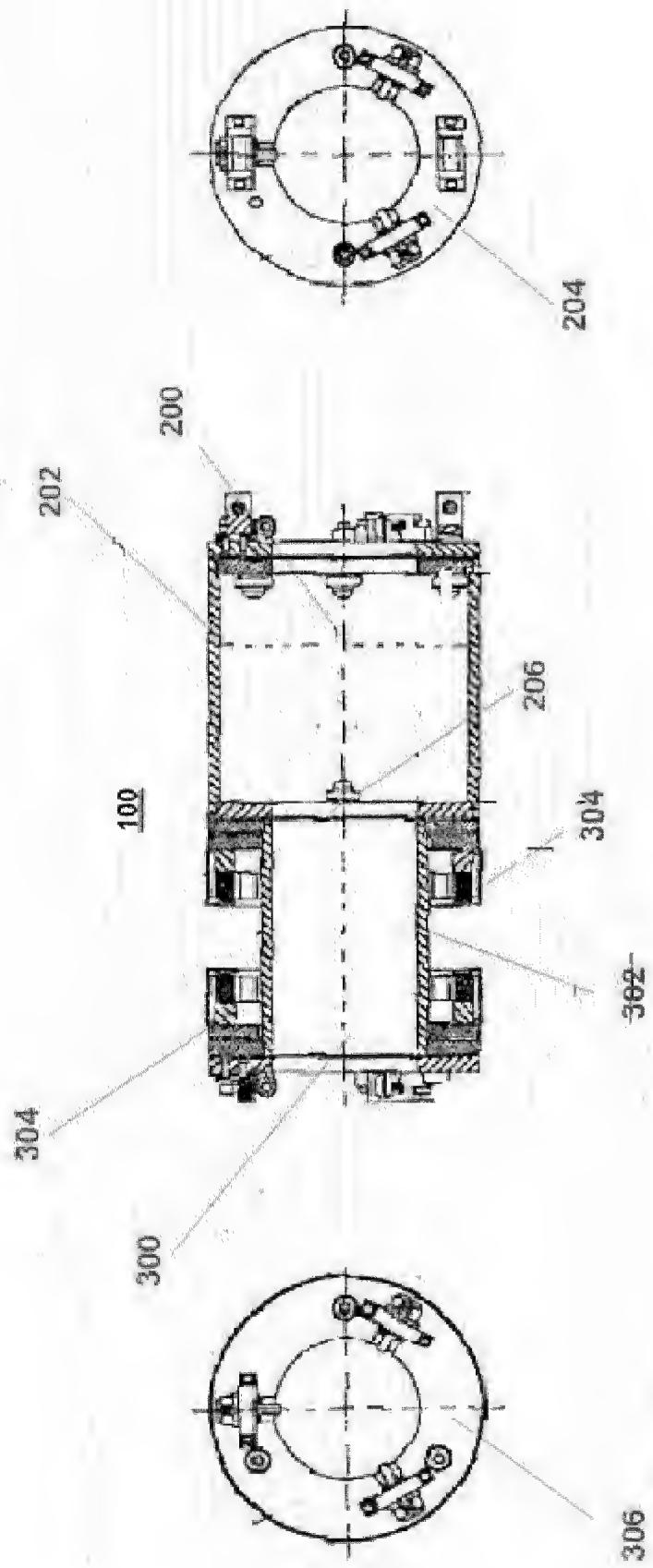


FIG. 2B

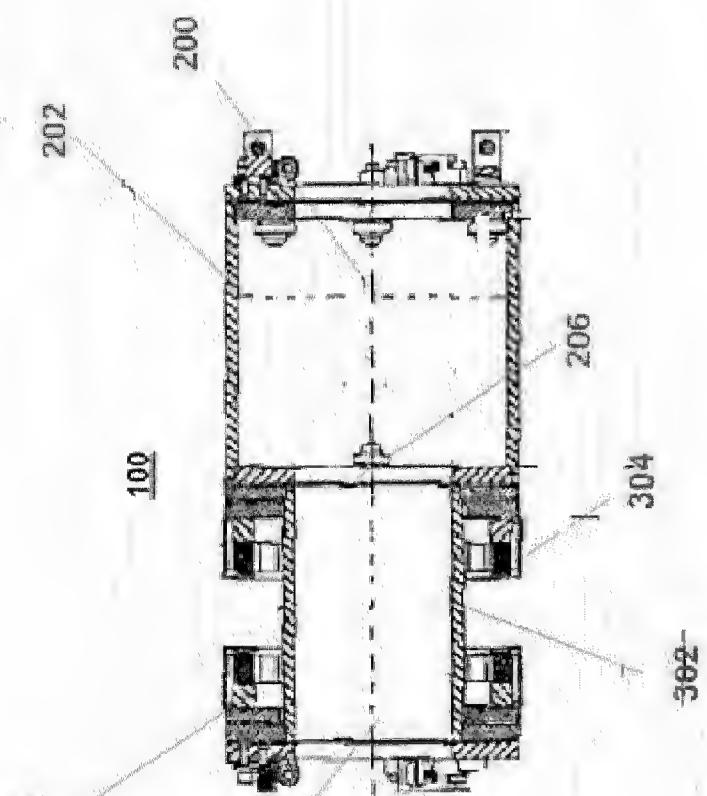
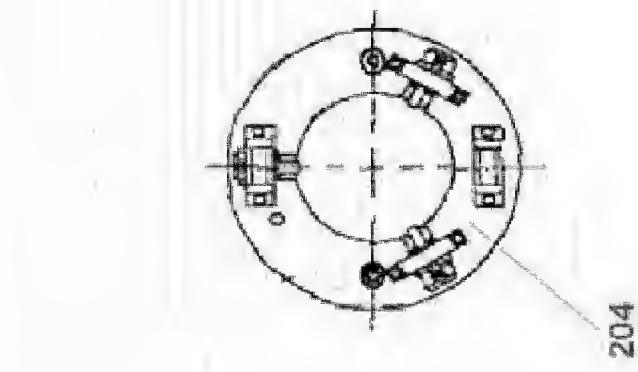


FIG. 2C



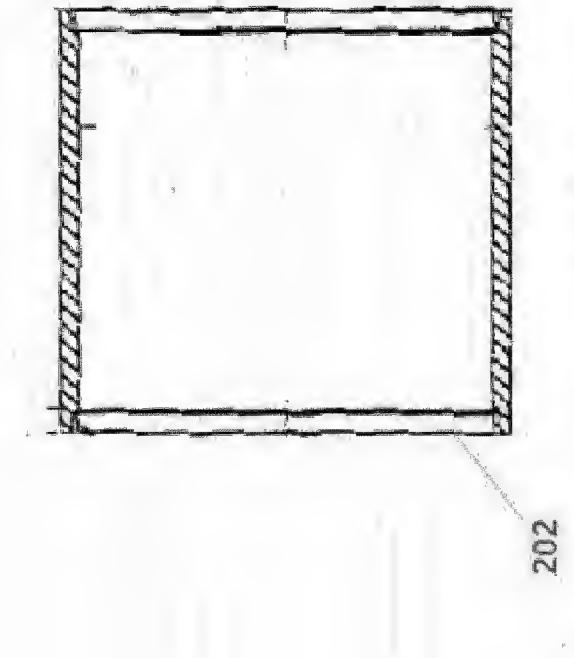


FIG. 3B

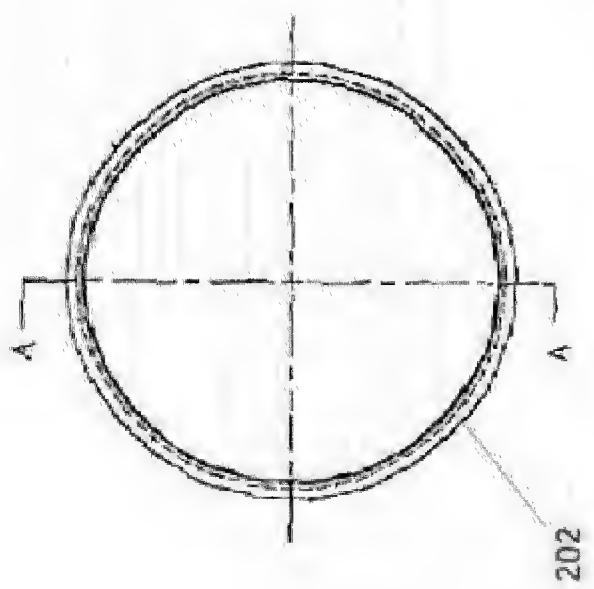


FIG. 3A

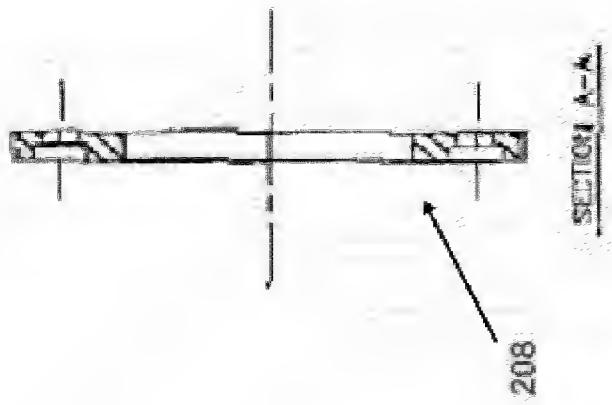


FIG. 4B

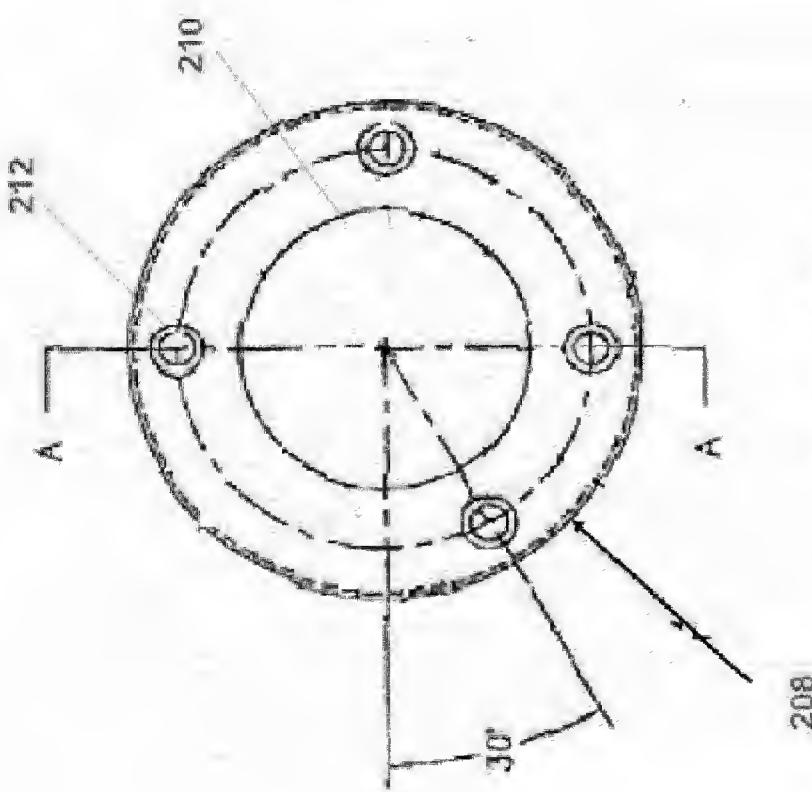


FIG. 4A

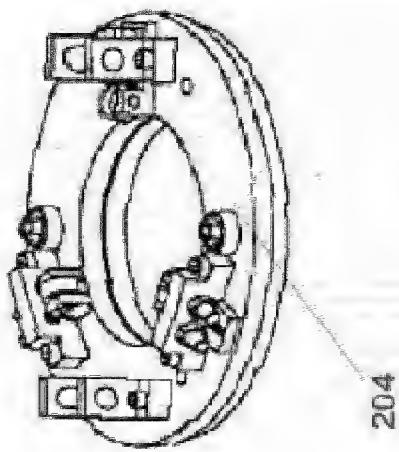


FIG. 5C

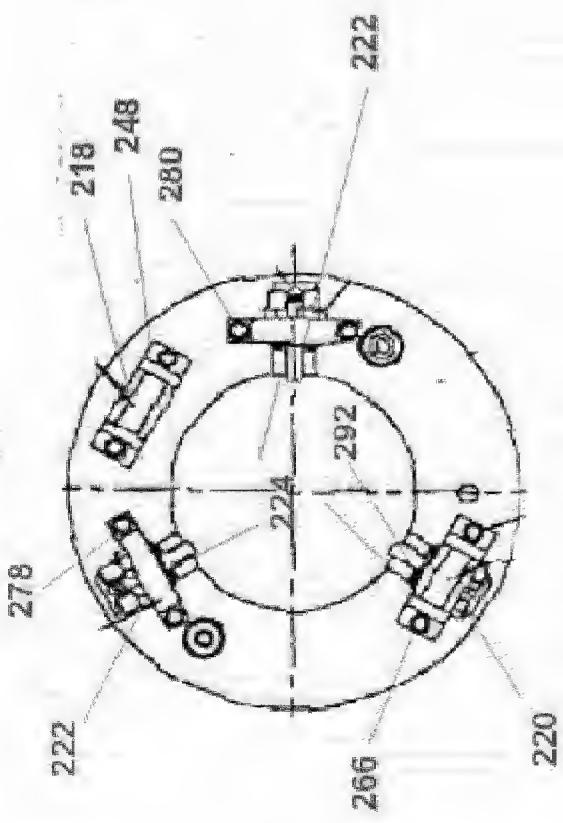


FIG. 5A

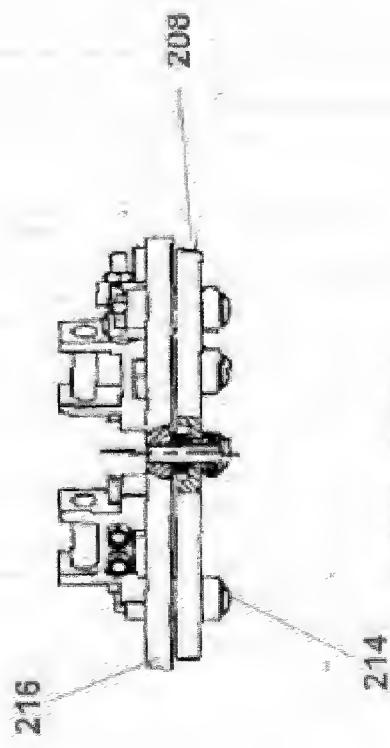


FIG. 5B

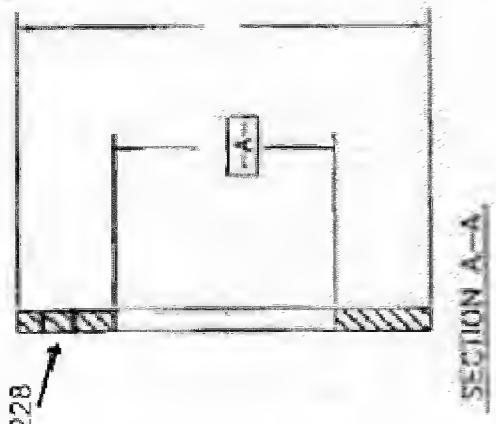


FIG. 6B

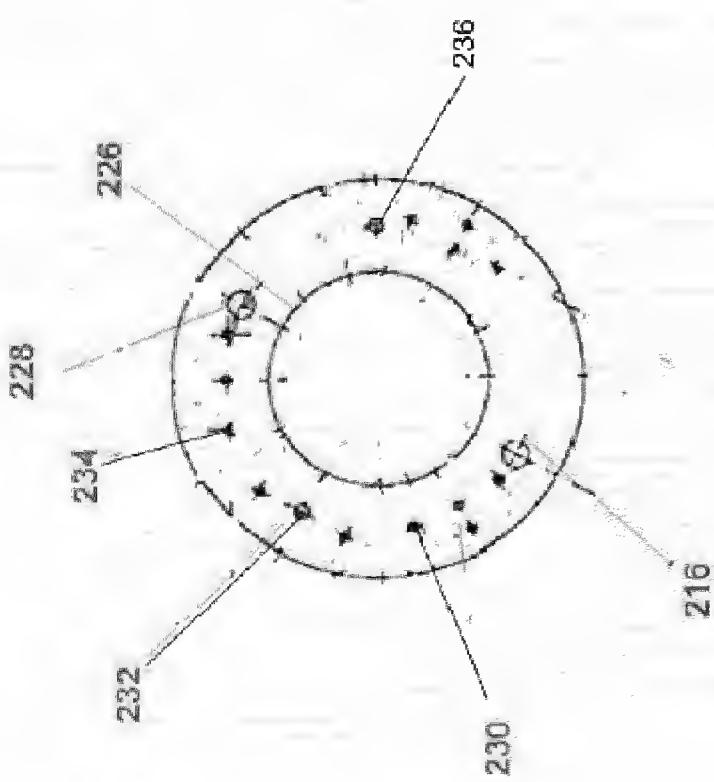


FIG. 6A

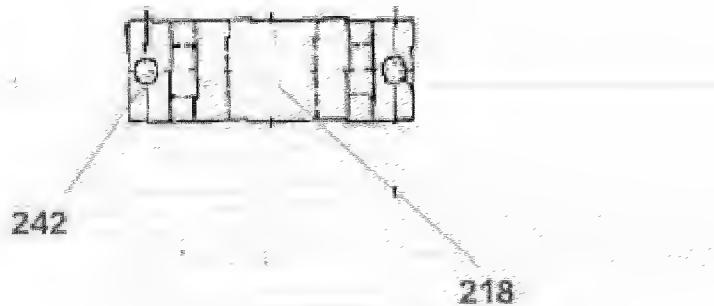


FIG. 7A

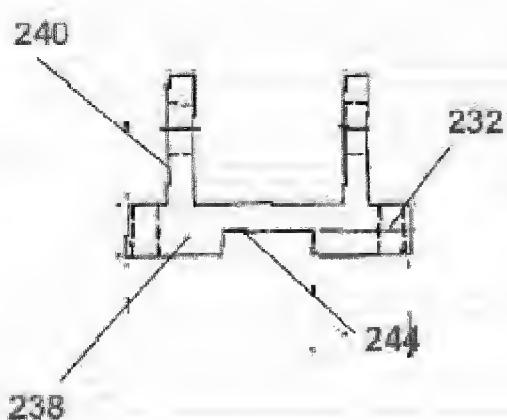


FIG. 7B

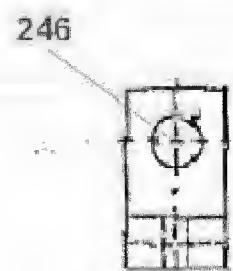


FIG. 7C

FIG. 8A

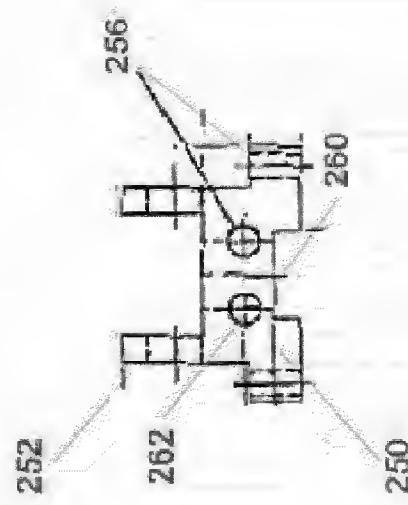
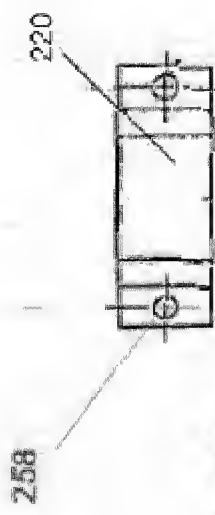
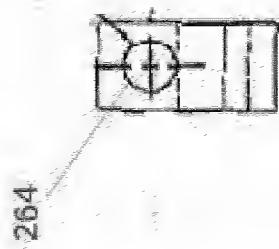


FIG. 8B

FIG. 8C



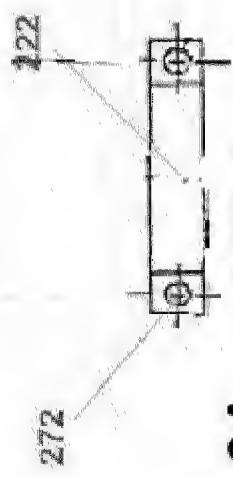


FIG. 9A

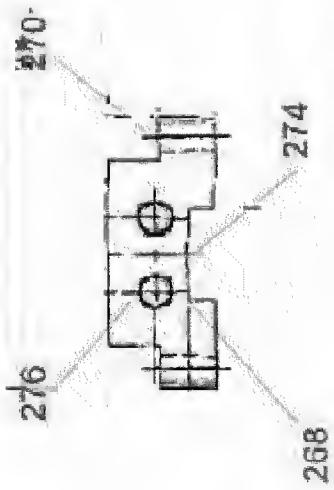


FIG. 9B



FIG. 9C

FIG. 10A

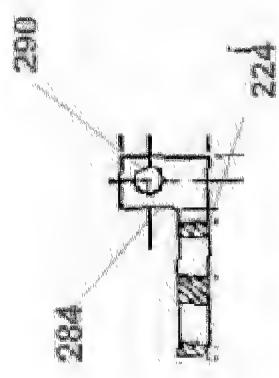
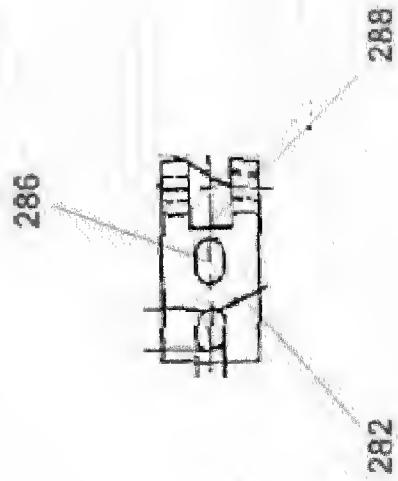
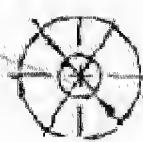


FIG. 10B



294



292

FIG. 11A

292

FIG. 11B



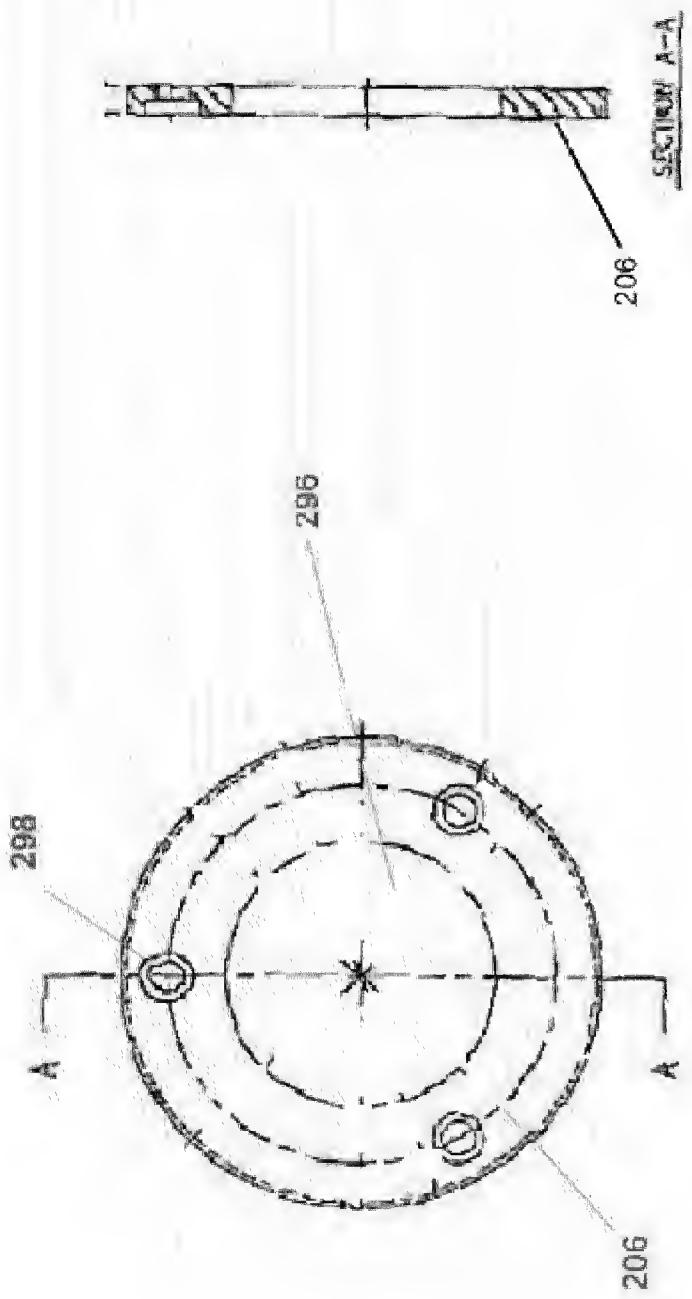
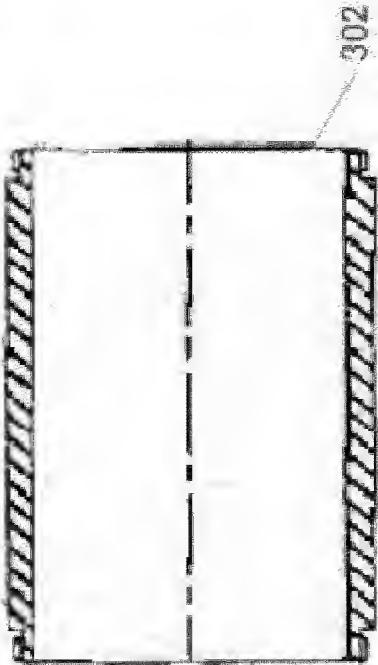


FIG. 12A

FIG. 12B



SECTION A-A

FIG. 13B

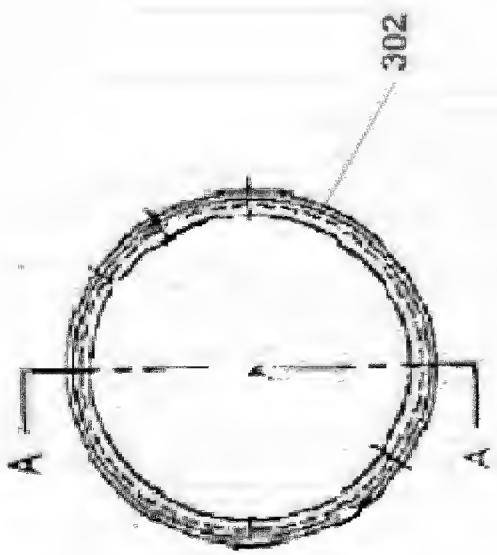


FIG. 13A

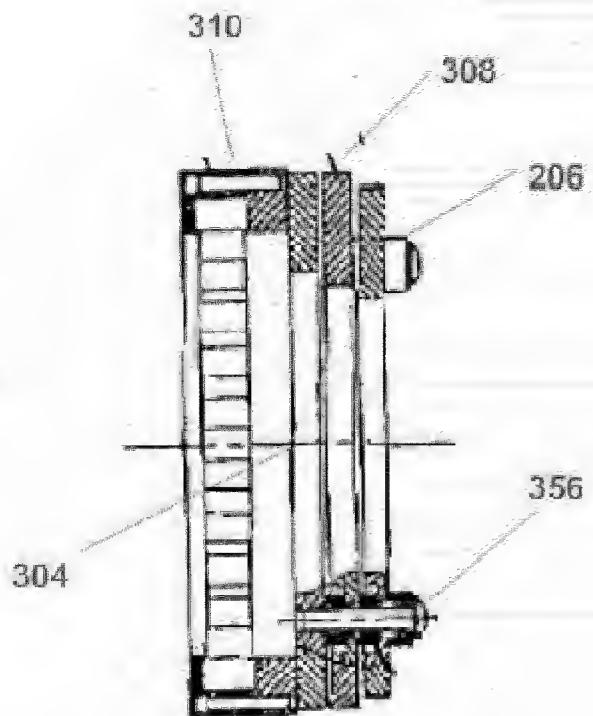


FIG. 14

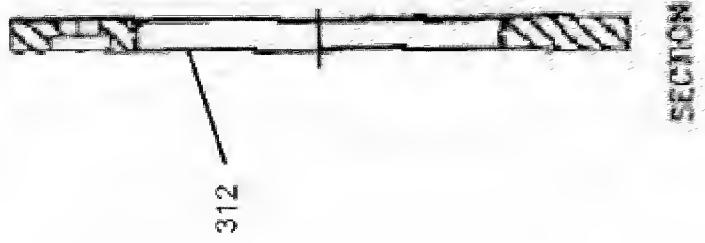


FIG. 15B

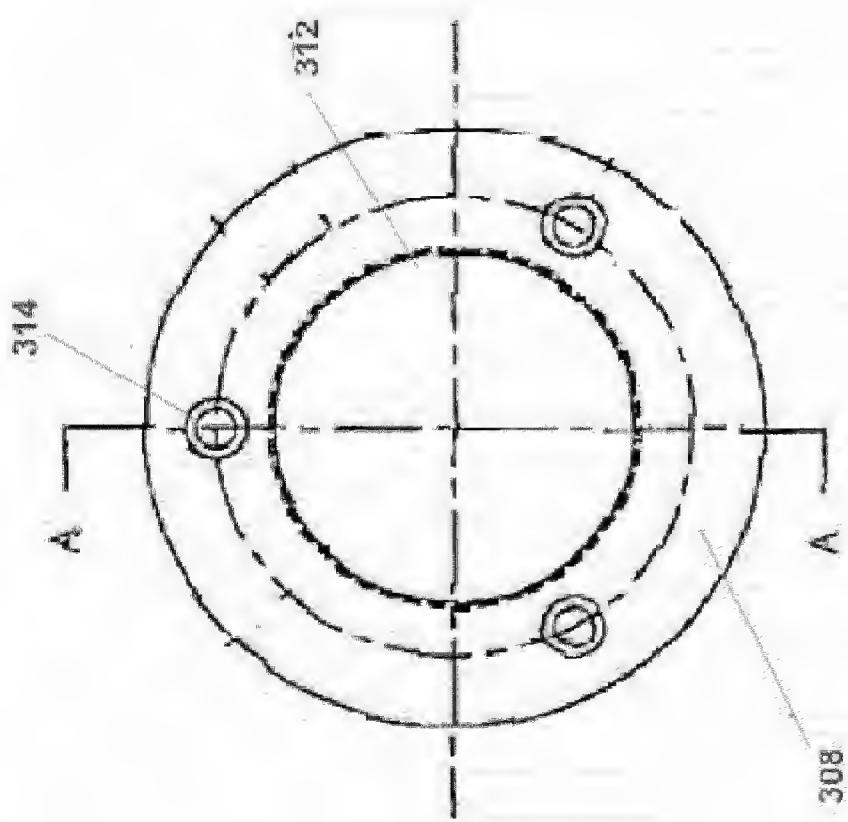


FIG. 15A

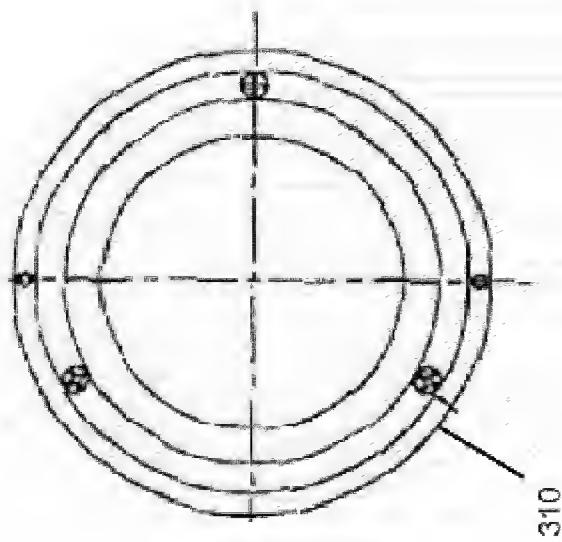


FIG. 16B

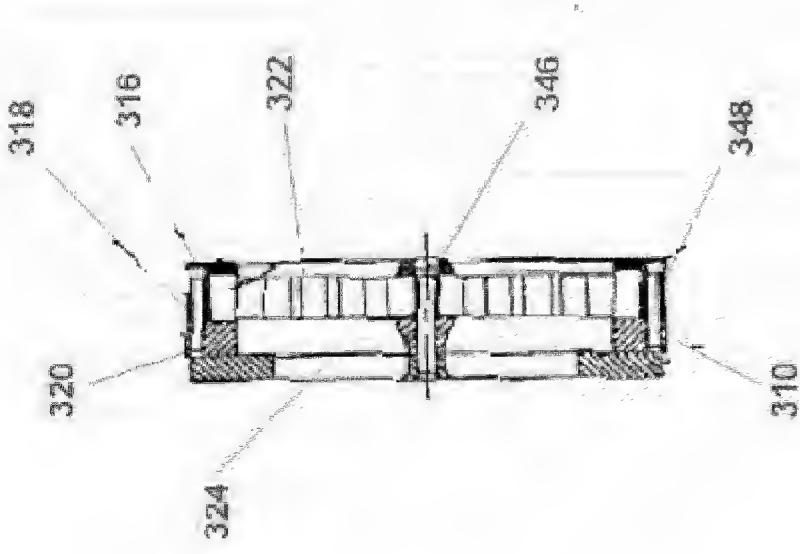


FIG 16A



SECTION A-A

FIG. 17B



SECTION B-B

FIG. 17C

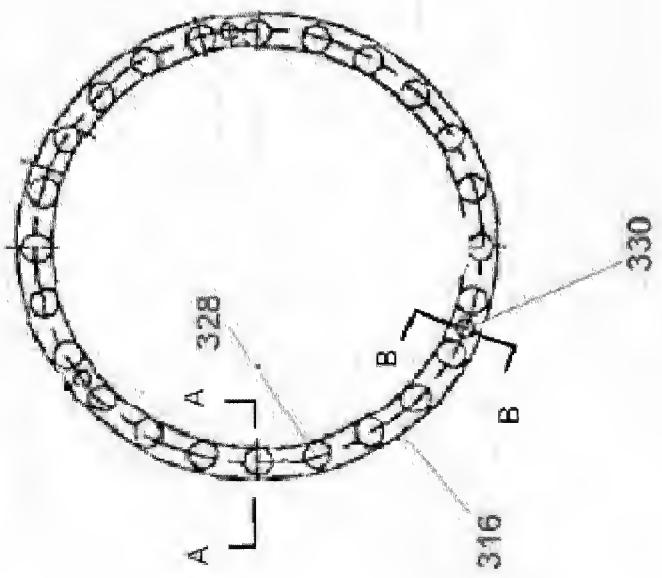
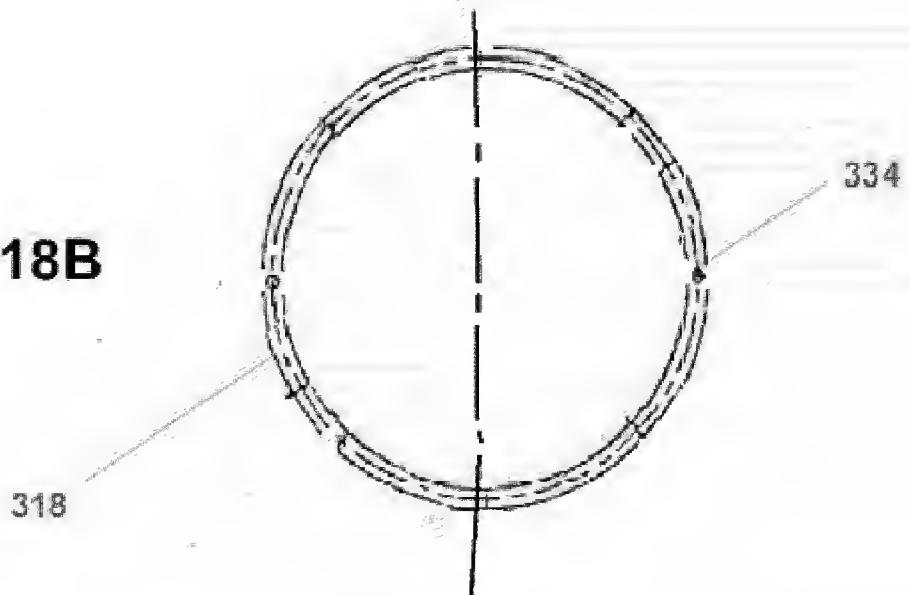


FIG. 17A



FIG. 18A

FIG. 18B



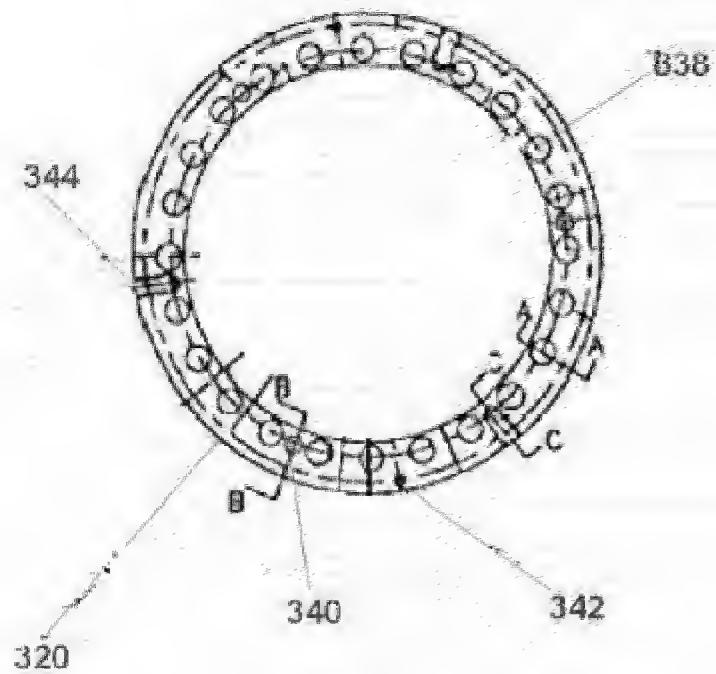


FIG. 19

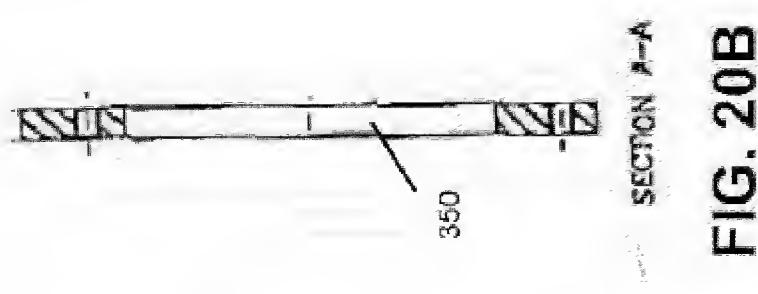
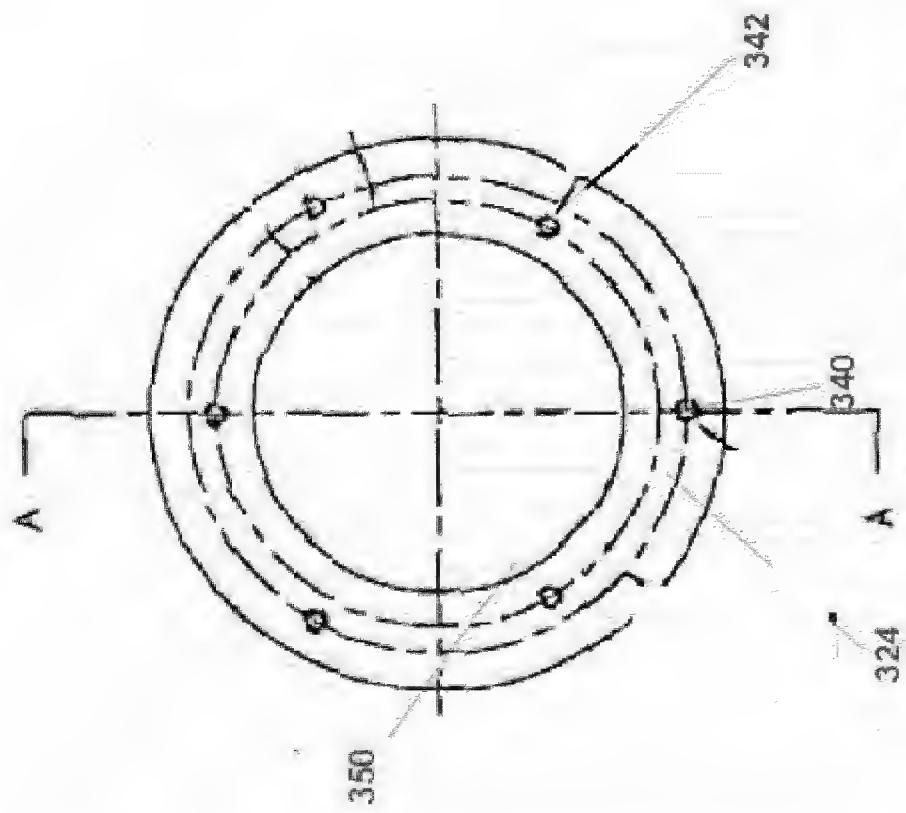


FIG. 20B

FIG. 21B

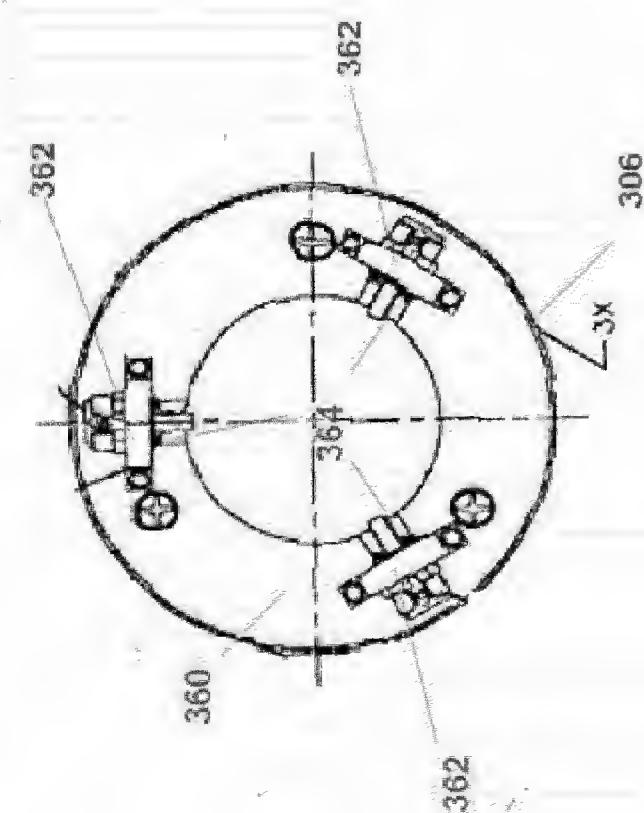
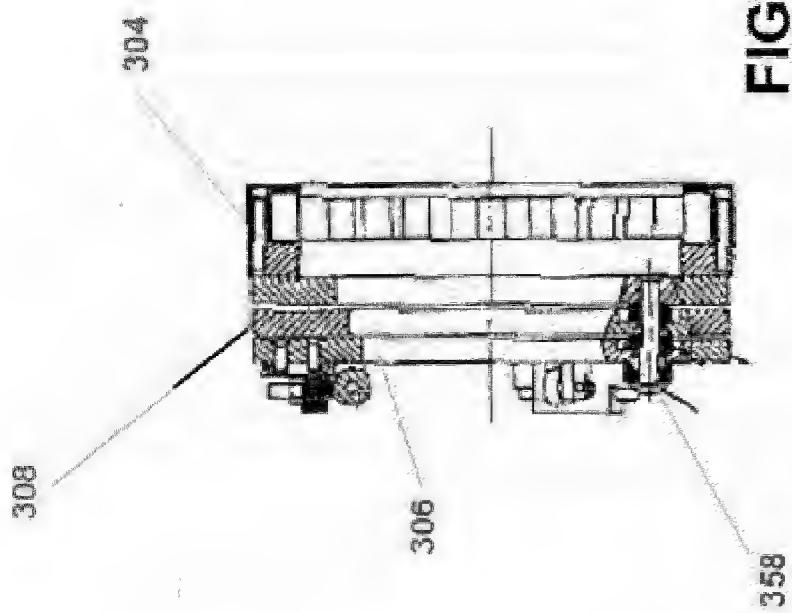


FIG. 21A

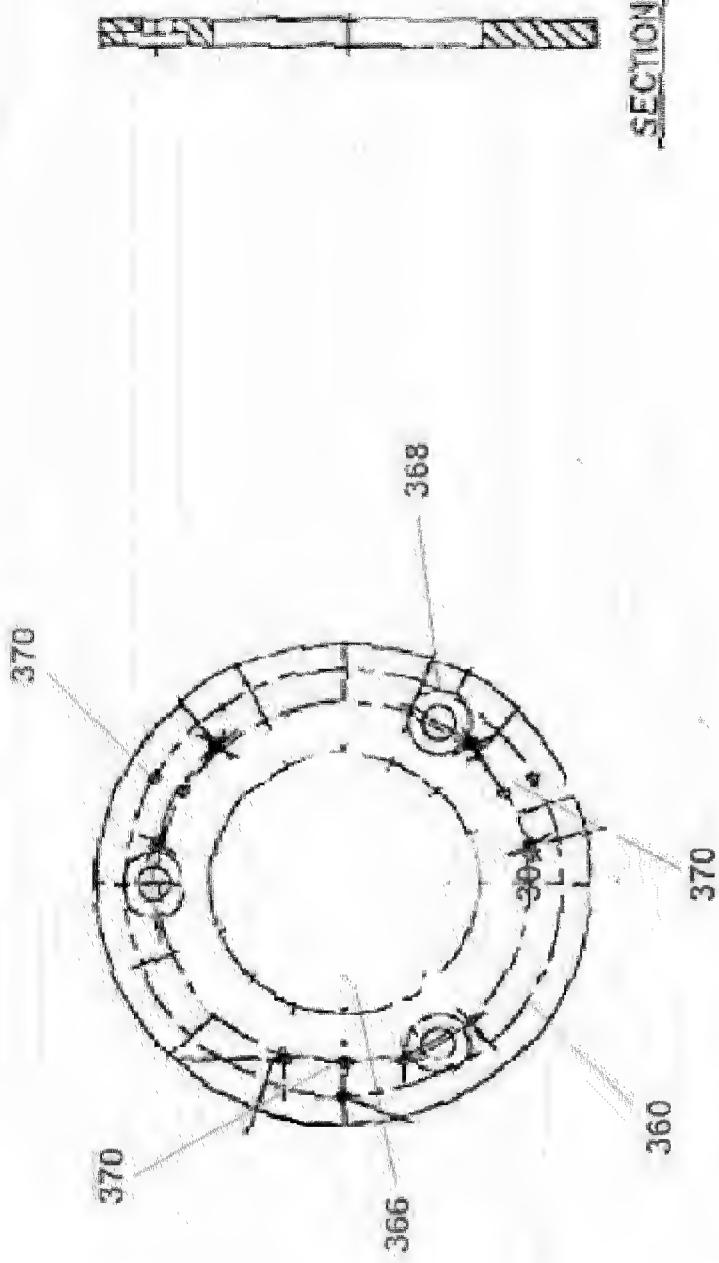


FIG. 22A

FIG. 22B

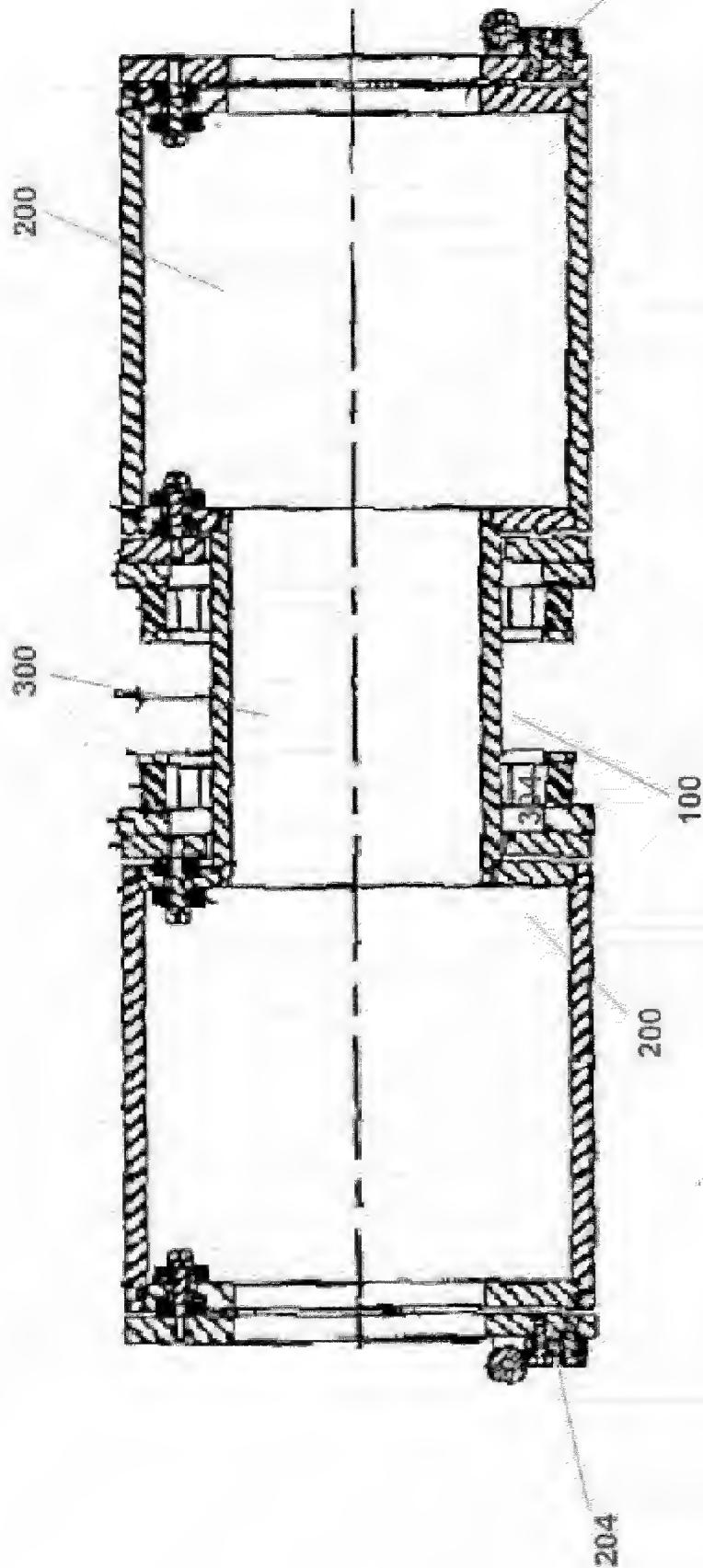


FIG. 23

FIG 24

SUBSTRATE 200 AND TARGET 250 ARE SURFACES TO BE CLEANED OF RESIDUAL CONTAMINATION OR A SET AMOUNT OF MATERIAL DEPTH. SURFACES CAN ALSO BE MODIFIED BY A PROCESS THAT IS CONTAINED WITHIN THE DEVICE.

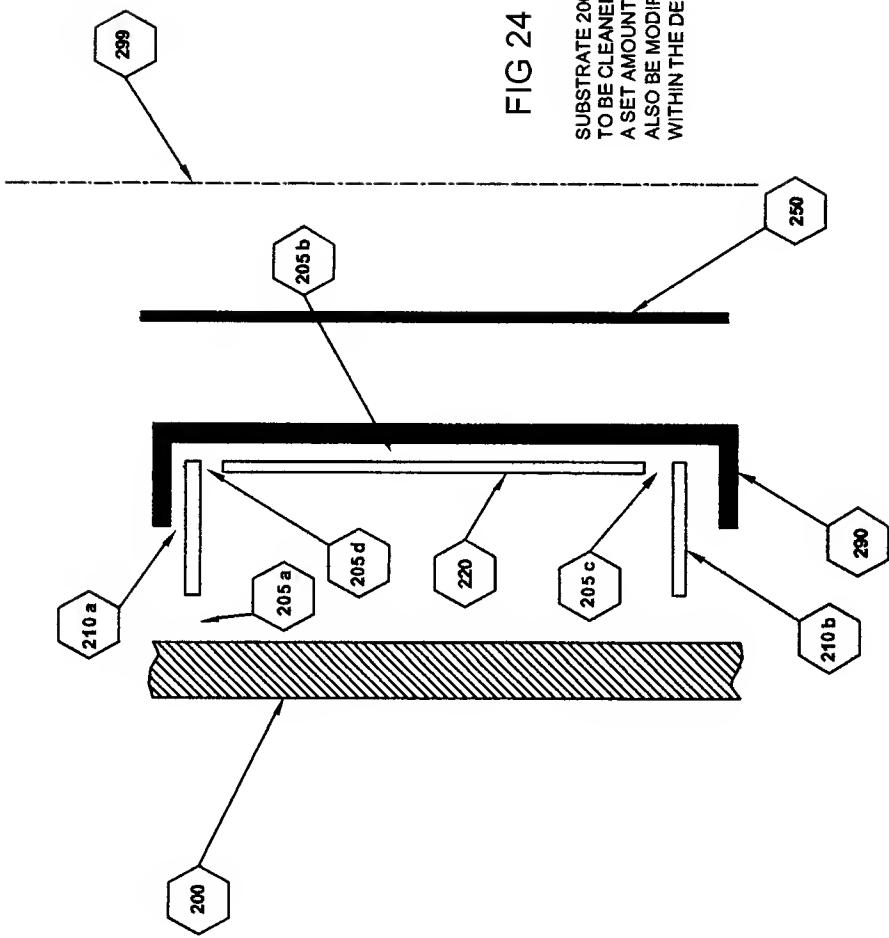


FIG 24

FIG 25
IS A CROSS SECTIONAL
VIEW OF THE PLASMA CLEANING
AND COLLECTION DEVICE
COMPRISED OF AN INTERNALLY
GENERATED MAGNETIC FIELD.
THE COLLECTION SURFACE IS
NUMBERED: 320, 310 a, AND 320 b.

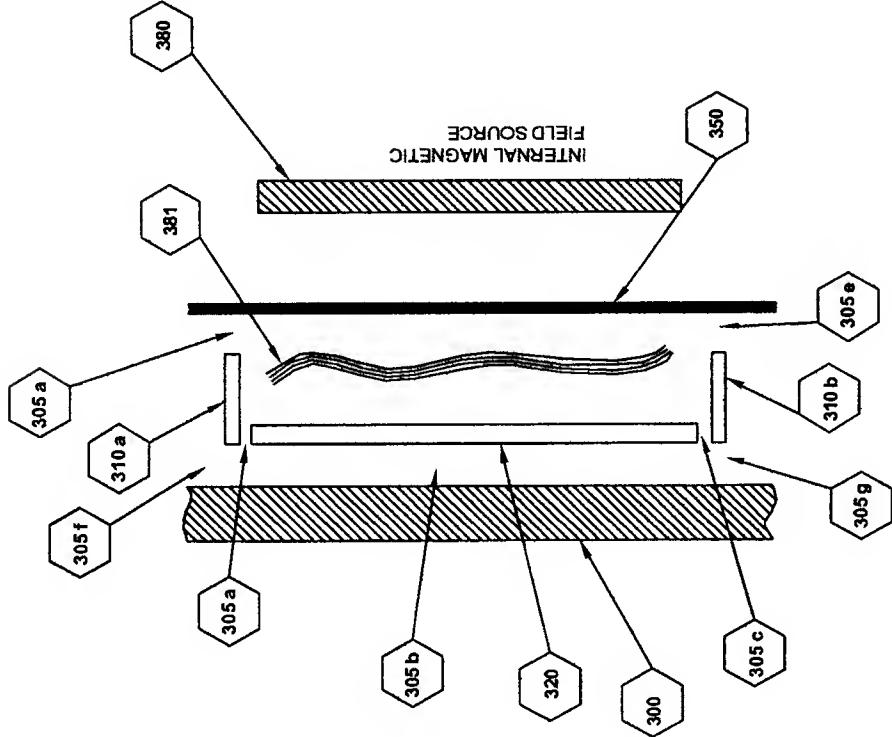
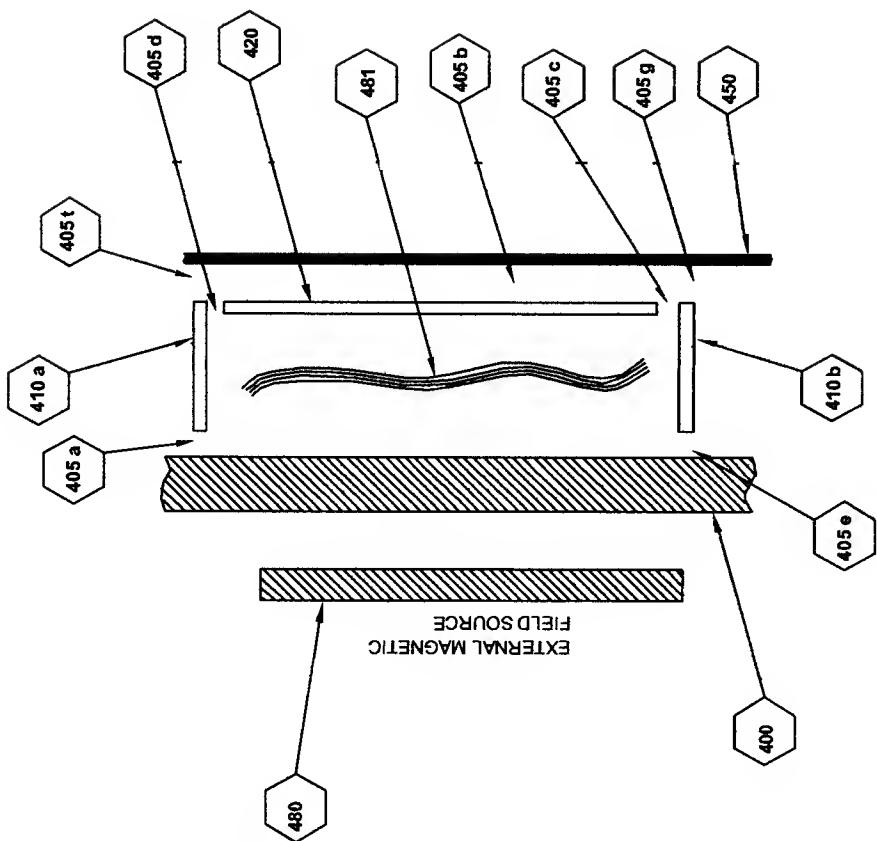


FIG 25

FIG 26



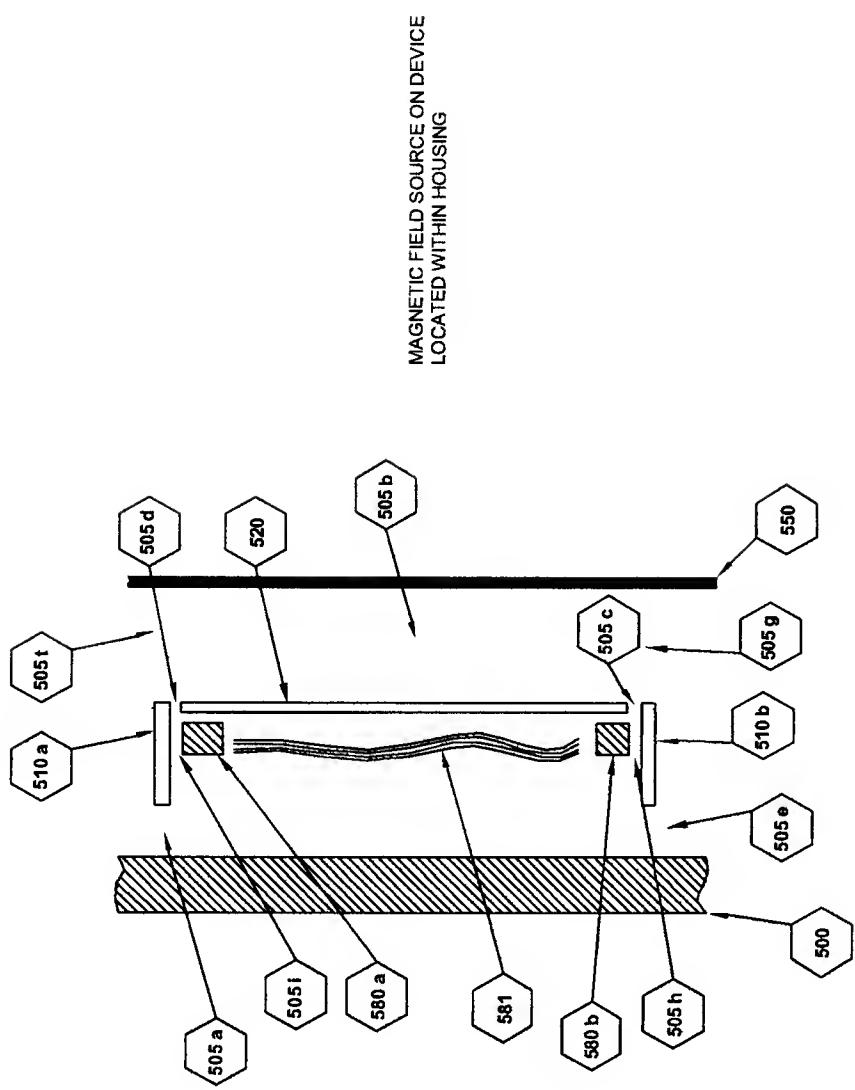


FIG 27